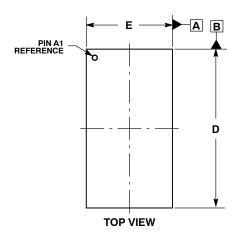
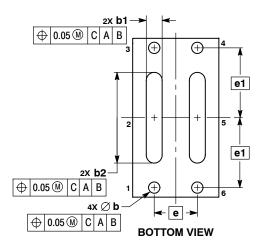


## WLCSP6 3.5x1.9x0.21 CASE 567SZ ISSUE A

**DATE 24 APR 2017** 







## NOTES:

- DIMENSIONING AND TOLERANCING PER
  ASME V14 5M 1994
- ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.19	0.21	0.23	
b	0.22	0.25	0.28	
b1	0.32	0.35	0.38	
b2	1.97	2.00	2.03	
D	3.47	3.50	3.53	
E	1.87	1.90	1.93	
е	0.95 BSC			
e1	1.54 BSC			

## GENERIC MARKING DIAGRAM\*



A = Assembly Location

′ = Year

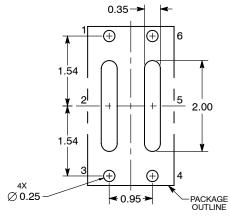
W = Work Week

ZZ = Assembly Lot

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " \*", may or may not be present. Some products may not follow the Generic Marking.

## RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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